Five-Day Delivery of Overmolded QFNs from Quik-Pak San Diego

Quick-Turn Engineering Builds of Custom Designs Available Five Weeks After Drawing Approval; QFNs on Display at APEC Conference in San Antonio, TX March 5-7, 2018 Booth #758 & GOMATECH Conference in Miami, FL March 12-15, 2018 Booth #318

San Diego, CA – March 5, 2018 – With the installation of a K&S IConn Plus wirebonder, molding press and laser marker at its San Diego, Calif. facility, Quik-Pak delivers assembled QFNs in five days. Quick-turn engineering builds for overmolded QFN packages are available in as little as five weeks after validation of the customer’s design.

Quik-Pak QFNs are available in over 35 designs, with multiple thicknesses. Package sizes range from 2x2 mm to 12x12 mm for QFNs, as well as 1.5x1.5 mm to 4x4 mm for DFNs. All are RoHS compliant and utilize NiPdAu-plated lead frames. An independent third-party laboratory confirmed multiple packages with different die attach materials passed MSL3 level criteria for mechanical integrity per IPC/JEDEC-J-STD-020E. Copies of the reports are available by request.

- Visit Quik-Pak at Booth #758 at APEC in San Antonio, March 5 – 7. APEC sessions will explore the latest practical and applied innovations in power electronics. Stop by the booth to see how our prototype and volume packaging and assembly services can provide solutions for your power electronics. Conference details are available at http://www.apec-conf.org.

- Quik-Pak will be exhibiting in Booth #318 at GOMACTech in Miami, Florida March 12 – 15. This year’s event will focus on microelectronics innovation and security along with specialization for government applications. Visit our booth in the exhibit hall to explore Quik-Pak’s capabilities. For more information and to register, please visit https://www.gomactech.net/2018/index.html.

- Join Quik-Pak at the Long Island RF / Microwave Symposium, Thursday, April 5 from noon-8pm. This free event offers technical lectures to explore trends in microwave, millimeter and RF technology along with the opportunity to learn about Quik-Pak capabilities during the exhibit hours. For more information visit https://ieee.li/microwave/.

ABOUT QUIK-PAK
Quik-Pak, a division of Promex, provides IC packaging, assembly and wafer preparation services in its ISO 9001:2008-certified, ITAR-registered facility in San Diego, California. The company’s overmolded QFN/DFN packages and premolded air cavity QFN packages provide a fast, convenient solution for prototype to full production needs. Same-day assembly services are provided to reduce time to market. More information is available at http://www.icproto.com or by calling 858-674-4676.

Media Contacts:
c3PR: Mar Junge 408-219-0101
Quik-Pak: Casey Krawiec 858-521-3607